



T Mysska	Hits	Search Text	DB	Time stamp
L Number	57683	metal with wire	USPAT;	2002/03/13 14:15
1 1	5/003	Werdt Miri Mile	US-PGPUB	2002,03/13 14.13
2	20507	metal near wire	USPAT;	2002/03/13 14:15
4	20307	modal field wife	US-PGPUB	-555,55,15 14.15
3	87240	metal same wire	USPAT;	2002/03/13 14:16
	0,240	model pame nilo	US-PGPUB	= 0.02, 30, 20 21.20
4	87240	(metal with wire) (metal near wire) (metal	USPAT;	2002/03/13 10:03
-	2,210	same wire)	US-PGPUB	
5	41286	((metal with wire) (metal near wire)	USPAT;	2002/03/13 14:18
-		(metal same wire)) and (insulat\$3	US-PGPUB	
		dielectric)		
6	5920	(((metal with wire) (metal near wire)	USPAT;	2002/03/13 14:18
		(metal same wire)) and (insulat\$3	US-PGPUB	
[dielectric)) and (mount\$3 same (chip dice		
		substrate))		
7	5588	((((metal with wire) (metal near wire)	USPAT;	2002/03/13 14:23
		(metal same wire)) and (insulat\$3	US-PGPUB	
		dielectric)) and (mount\$3 same (chip dice		
		substrate))) and (via contact hole)		0000/07/17
8	4166	((((metal with wire) (metal near wire)	USPAT;	2002/03/13 14:24
		(metal same wire)) and (insulat\$3	US-PGPUB	
İ		dielectric)) and (mount\$3 same (chip dice		
	F3.50	substrate))) and (open\$4 recess trench)	HODE	2000/02/12 12 22
9	5750	(((((metal with wire) (metal near wire)	USPAT;	2002/03/13 10:08
		(metal same wire)) and (insulat\$3	US-PGPUB	
		dielectric)) and (mount\$3 same (chip dice		
		substrate))) and (via contact hole))		
		(((((metal with wire) (metal near wire)		
		<pre>(metal same wire)) and (insulat\$3 dielectric)) and (mount\$3 same (chip dice</pre>		
		substrate))) and (open\$4 recess trench))		
10	5561	((((((metal with wire) (metal near wire)	USPAT;	2002/03/13 10:09
**	2201	(metal same wire) and (insulat\$3	US-PGPUB	2002/03/13 10:09
		dielectric)) and (mount\$3 same (chip dice	00 10100	
		substrate))) and (via contact hole))		
		(((((metal with wire) (metal near wire)		
		(metal same wire)) and (insulat\$3		
		dielectric)) and (mount\$3 same (chip dice		
		substrate))) and (open\$4 recess trench)))		
		and connect\$3		
11	2649	((((((metal with wire) (metal near wire)	USPAT;	2002/03/13 10:11
		(metal same wire)) and (insulat\$3	US-PGPUB	
		dielectric)) and (mount\$3 same (chip dice		
		substrate))) and (via contact hole))		
		(((((metal with wire) (metal near wire)		
		(metal same wire)) and (insulat\$3		
		dielectric)) and (mount\$3 same (chip dice	ĺ	
	ĺ	substrate))) and (open\$4 recess trench)))		
1		and connect\$3) and electrode		
12	2613	(((((((metal with wire) (metal near wire)	USPAT;	2002/03/13 13:34
		(metal same wire)) and (insulat\$3	US-PGPUB	
İ		dielectric)) and (mount\$3 same (chip dice		
	ļ	<pre>substrate))) and (via contact hole))</pre>	}	
		(((((metal with wire) (metal near wire)		
1		(metal same wire)) and (insulat\$3		
		dielectric)) and (mount\$3 same (chip dice		
		<pre>substrate))) and (open\$4 recess trench)))</pre>		
		and connect\$3) and electrode) and (base		
14	F0053	substrate plate glass)		0000 (02 (4 0 - : : :
14	59257	metal with wire	EPO; JPO;	2002/03/13 14:17
			DERWENT;	
15	10560	motal near wine	IBM_TDB	2002/02/12 14 15
10	19562	metal near wire	EPO; JPO;	2002/03/13 14:15
1			DERWENT;	
16	73512	metal same wire	IBM_TDB EPO; JPO;	2002/03/13 14:16
10	13312	Wefat same with		2002/03/13 14:16
			DERWENT; IBM TDB	
			דמת דמם ד	

17	73512	(metal with wire) (metal near wire) (metal	EPO; JPO;	2002/03/13 14:17
		same wire)	DERWENT;	
			IBM_TDB	
18	15788	((metal with wire) (metal near wire)	EPO; JPO;	2002/03/13 14:18
		(metal same wire)) and (insulat\$3	DERWENT;	
		dielectric)	IBM_TDB	
19	665	(((metal with wire) (metal near wire)	EPO; JPO;	2002/03/13 14:19
1		(metal same wire)) and (insulat\$3	DERWENT;	
i		dielectric)) and (mount\$3 same (chip dice	IBM_TDB	
		substrate))		
20	292	((((metal with wire) (metal near wire)	EPO; JPO;	2002/03/13 14:23
		(metal same wire)) and (insulat\$3	DERWENT;	
		dielectric)) and (mount\$3 same (chip dice	IBM_TDB	
		substrate))) and (via contact hole)		
21	99	(((((((((((((((((((((((((((((((((((((((EPO; JPO;	2002/03/13 14:24
		(metal same wire)) and (insulat\$3	DERWENT;	
	,	dielectric)) and (mount\$3 same (chip dice	IBM_TDB	
		substrate))) and (open\$4 recess trench)		
22	340	((((())))	EPO; JPO;	2002/03/13 14:25
		(metal same wire)) and (insulat\$3	DERWENT;	
		dielectric)) and (mount\$3 same (chip dice	IBM_TDB	ł
		substrate))) and (via contact hole))		
		(((((metal with wire) (metal near wire)		
		(metal same wire)) and (insulat\$3		
		dielectric)) and (mount\$3 same (chip dice		
		<pre>substrate))) and (open\$4 recess trench))</pre>		